Solderless Breadboard





Specifications

Board Type : Prototype Board Total Number of Tie Points : 2420 Tie Points

Board Material : Epoxy Glass Composite

No. of Distribution Strips / Buses : 5 Bus Strips
No. of Terminal Strips : 3 Terminal Strip
Board Dimensions (L × W) : 166mm × 55mm

Pitch : 2.54mm

Part Number Table

Description	Part Number
Breadboard, 8.5mm Thickness, 183mm × 165mm	21-18946

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